ACCRETECH

W-GM-5200

Wafer Edge Grinding Machine

- Best Seller Machine W-GM-Series
- Improve the Space Efficiency by the Compact Design
- Highly Accurate Grinding by the Synchronized X・Y・θ Support Control
- Easy Operation by Touch Panel
- Measuring of Grinding Result and Automatic Correction

TOKYO SEIMITSU CO., LTD.

W-GM-5200 Specification

Basic Specification

Wafer size	Φ300 mm
Wafer thickness	0.6 - 1.0 mm
Wafer shape	Φ300 mm (with notch)
Peipheral Grinding	
Outer diameter (groove)	Φ200 mm
Outer diameter (periphery)	Φ202 mm
Inner diameter	ϕ30 mm
Flange thickness	20 mm
Spindle frequency	5000 rpm
Spindle bearing system	Grease lubrication,mechanical bearing system
Spindle driving system	Built-in system
Grinding speed	Any setting possible
Notch grinding	
Outer diameter (groove)	Φ1.8-2.4 mm
Outer diameter (periphery)	Φ3.8 mm
Shank diameter	Φ3 mm
Spindle frequency	80000 rpm
Spindle bearing system	Air bearing system
Spindle driving system	Air turbine system
Signal tower	3-color indicator (the color and flashing / lighting can be changed by key input)

Option

Low Damage Grinding System	
Spindle frequency	36000 rpm
Spindle bearing system	Air bearing system
Spindle driving system	High Frequency Built-in System
Notch Fine spindle frequency	150000 rpm
Spindle bearing system	Air bearing system
Spindle driving system	High Frequency Built-in System
Wheel profile (Periphery fine)	
Groove Diameter	Φ46.6-42 mm
Outer Diameter	Φ50 mm
Flange Thickness	15 mm
Wheel profile (Notch fine)	
Groove Diameter	Φ1.8 - 2.2 mm
Outer Diameter	Φ3.8
Shank Diameter	Φ3 mm

Mechanical specifications

Wafer thickness measurement	
Resolution	1 μm
Repeated measurement accuracy	Within ±2 μm
Measuring system	Non-contact system
Alignment mechanism	
System	Laser measuring system
Resolution	1μm
Centering accuracy	Within ±50 μm
Grinding table linear axis (X / Y / Z)	
Resolution	1μm
Driving system	AC servomotor and ball screw
Grinding table revolution axis (θ)	
Resolution	0.001°
Driving system	DD motor and higt resolution mechanism
Grinding table flatness	
Surface fluctuation	Less than 10 μm / 360°
Transfer unit	
Conveying system	Suction conveying system
Vacuum generating source	Vacuum ejector
Wafer identifying sensor	Vacuum sensor
Cleaning unit	
Cleaning system	Spinner cleaning
Drying system	Dry air system
Driving system	AC servomotor
Revolution speed	500-1500 min^{-1}
Loading and unloading unit	
Type	Cassette carrier type (with options)

Other specifications

Dimensions,Weight	
W-GM-5200-3C	2515 (W) x 1475 (D) x 2000 (H) / *2300mm 5000kg *including the signal tower
W-GM-5200-8C	3040 (W) x 1775 (D) x 2000 (H) / *2300mm 5000kg *including the signal tower

ACCRETECH

Japan / Head Office Tokyo Seimitsu Co., Ltd.
2968-2, Ishikawa-machi, Hachioji-shi, Tokyo,192-8515 Japan
TEL：(042) 642-1701 FAX：(042) 642-1798
https://www.accretech.com/en/

Contact information